sapcon®

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material UL Flammability 94V-O



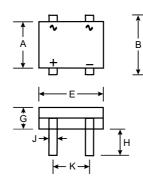
Case: MB-S, Molded Plastic

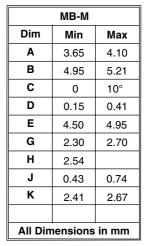
Terminals: Plated Leads Solderable per

MIL-STD-202, Method 208
Polarity: As Marked on Case
Weight: 0.22 grams (approx.)

Mounting Position: AnyMarking: Type Number

• Lead Free: For RoHS / Lead Free Version,







Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

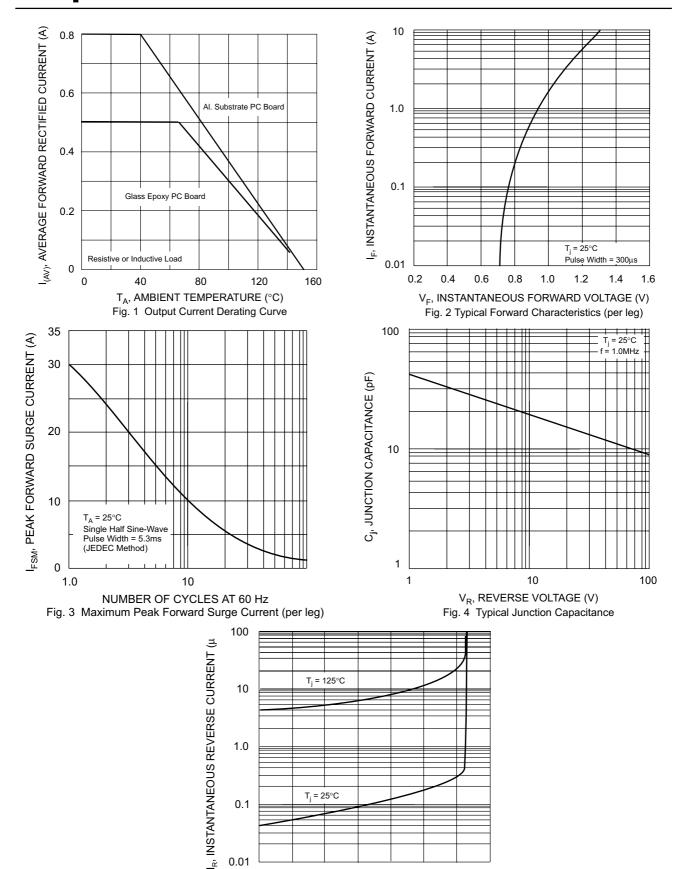
Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbo	MB05M	MB1M	MB2M	MB4M	МВ6М	MB8M	MB10M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	VR(RMS)	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) $@T_A = 40^{\circ}C$ Average Rectified Output Current (Note 2) $@T_A = 40^{\circ}C$	lo	0.5 0.8							А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	30							А
I ² t Rating for Fusing (t < 8.3ms)	l²t	5.0						A ² s	
Forward Voltage per element @I _F = 0.5A	VFM	1.0							V
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	lrм	5.0 500							μA
Typical Junction Capacitance per leg (Note 3)	Cj	13							pF
Typical Thermal Resistance per leg (Note 1)	RθJA RθJL	70 20							°C/W
Operating and Storage Temperature Range	Tj, TSTG	-55 to +150							°C

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

- 2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.
- 3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

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80

100

120

60

40

0.01

20